AMENDMENTS TO THE CLAIMS:

1. (currently amended) A heat-resistant insulating film, comprising:

a film comprising a pattern profile corresponding to a structure with geometries including a convex or concave portion, the pattern profile being formed by three-dimensional forming for fitting onto the structure;

wherein a material of the film comprises a polyimide.

2. (canceled)

3. (currently amended) The heat-resistant insulating film according to claim 1, wherein the pattern profile ~~includes~~ comprises an uneven profile having a ratio of a depth to an opening width less than or equal to two.

4. (currently amended) The heat-resistant insulating film according to claim 1, wherein the structure [[is]] comprises a circuit board mounted with electronic components on the board.

5. (currently amended) The heat-resistant insulating film according to claim 1, wherein the three-dimensional forming [[is]] comprises ~~vacuum/compressed~~ at least one of vacuum and compressed air forming.

6. (currently amended) The heat-resistant insulating film according to claim 1, wherein the three-dimensional forming [[is]] comprises pressure forming using a die.

7 – 12 (canceled)

13. (new) The heat-resistant insulating film of claim 1, wherein said film is fittable to a surface of said structure.

14. (new) The heat-resistant insulating film of claim 1, wherein said film comprises a formed film.

15. (new) The heat-resistant insulating film of claim 1, wherein said film is separately formed from said structure.

16. (new) A heat-resistant insulating film comprising a pattern profile corresponding to a structure, wherein the pattern profile comprises an uneven profile having a ratio of a depth to an opening width less than or equal to two.

17. (new) The heat-insulating film according to claim 16, wherein the pattern profile comprises geometries including a convex portion.

18. (new) The heat-insulating film according to claim 16, wherein the pattern profile comprises geometries including a concave portion.

19. (new) The heat-resistant insulating film according to claim 16, wherein the pattern profile is formed by three-dimensional forming for fitting onto the structure.

20. (new) The heat-resistant insulating film according to claim 16, wherein a material of the film comprises a resin with heat-resistance.

21. (new) The heat-resistant insulating film according to claim 20, wherein said resin with heat-resistance comprises one of polyimide, polyamide, polybenzimidazole, polyester, polyimidazole, polyphenylenesulfide, polyamideimide, polyetherimide, polyethelketone, and polysulphon.

22. (new) The heat-resistant insulating film of claim 16, wherein said film is fittable to a surface of said structure.

23. (new) The heat-resistant insulating film of claim 16, wherein said film comprises a formed film.

24. (new) The heat-resistant insulating film of claim 16, wherein said film is separately formed from said structure.

25. (new) A device for insulating a surface having an uneven profile, comprising

an insulating film formed to substantially correspond to the uneven profile, wherein said insulating film is fittable directly onto the surface to be insulated.

26. (new) The device for insulating a surface according to claim 25, wherein said insulating film comprises a high-functionality heat-resistant resin.

27. (new) The device for insulating a surface according to claim 26, wherein said high-functionality heat-resistant film comprises one of polyimide, polyamide, polybenzimidazole, polyester, polyimidazole, polyphenylenesulfide, polyamideimide, polyetherimide, polyethelketone, and polysulphon.